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-	88	jtag and (device with id\$2) and (reconfigur\$7 or configur\$7) and software	USPAT	2002/05/01 15:06
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-	9	((boundary adj2 scan or test adj access adj port or tap) same (id or identification or code)) same voltage) same pin\$2	USPAT	2002/07/02 15:25
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Electronics Manufacturing Technology Symposium, 1996., Nineteenth IEEE/CP

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Integrated Reliability Workshop, 1994. Final Report., 1994 International , 199

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Okuno, A.

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3 Recent progress in flexible moulding and reliability investigation f BGA-packages using advanced interconnection technology

Ansorge, F.; Becker, K.-F.; Ehrlich, R.; Azdasht, G.; Bader, V.; Aschenbrenne Reichl, H.

Polymeric Electronics Packaging, 1997. Proceedings., The First IEEE Internatio Symposium on , 1997

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26 New thin plastic package crack mechanism, induced by hot IC die Marks, M.R.

Reliability Physics Symposium 1992. 30th Annual Proceedings., International Page(s): 190 -197

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27 Chip on tape qualification and reliability

Wang, T.-C.; Long, J.; Kwong, P.

Multi-Chip Module Conference, 1992. MCMC-92, Proceedings 1992 IEEE , 199 Page(s): 72 -74

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